

semiconductor packaging news

EV Group Expands Production Capacity at Corporate Headquarters – November 30, 2023

semiconductor packaging news

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November 30, 2023

[U.S. Chipmakers a Decade Away From China Independence](#)

Nvidia CEO, Jensen Huang, has stated that global chipmakers are a decade away from achieving independence from China. He emphasized the urgent need for the United States and its allies to invest in domestic semiconductor manufacturing to reduce reliance on ...

CNBC



[SUMMARY](#)

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[Making Heterogeneous Integration More Predictable](#)

The article discusses efforts to enhance the predictability of heterogeneous integration, a critical aspect of semiconductor ...

Semiconductor Engineering

[SUMMARY](#)

[Revising 5G RF Calibration Procedures For RF IC Production Testing](#)

The non-ideal nature of items in the paths between the instruments and the device under test can degrade measurement accuracy.

Technical Paper

[DOWNLOAD](#)

[Worldwide Smartphone Shipments Finally Turn the Corner with 7.3% Growth Forecast in Q4 2023 and 3.8% in 2024, According to IDC Mobile Phone Tracker](#)

The International Data Corporation (IDC) predicts a 7.3% year-over-year growth in worldwide smartphone shipments for the ...

IDC

[SUMMARY](#)

Technical Papers

- [Revising 5G RF Calibration Procedures For RF IC Production Testing](#)
- [Optimizing New Power Switch Technology Using Compound Semiconductors](#)
- [Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages](#)
- [How AiP/AoP Technology Helps Enable 5G And More](#)
- [Decapsulation of Multi-Tier Wire-Bonded Semiconductors](#)
- [Series B : Adhesion and Bondability of Al2O3-coated Bonding Wire](#)
- [How to Select RF Test Socket](#)

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PacTech's LAPLACE technology

LASerPLACement. High accuracy and fine pitch placement & laser bonding using localized laser heating mechanism. The temp for laser reflow can be applied in the interconnection areas.
PacTech



6G to Bring Physical, Digital Worlds Closer, Experts Say

The emergence of 6G technology is poised to bridge the gap between the physical and digital ...
EE Times

SUMMARY

Nvidia CEO Jensen Huang says AI will be 'fairly competitive' with humans in 5 years

Nvidia CEO, Jensen Huang, predicts that artificial intelligence (AI) will reach a significant milestone within the ...
CNBC

SUMMARY

Chips in Cars, China's Semiconductor Surge, Mussel-Inspired Solution for Rare Earth Elements, From Earth to Moon and Everest in Pennies

China is witnessing a semiconductor surge, as the country focuses on increasing chip production for automobiles. ...
SEMI

SUMMARY



Amazon updates homegrown chips

Amazon Web Services (AWS) is taking steps to secure a stable supply of data-center processors by ...
Taipei Times

SUMMARY

California chipmaker pledges to hire unionized workers

California semiconductor firm, Akash Systems Inc, is breaking industry norms by planning to hire hundreds of ...
Taipei Times

SUMMARY

Discover the Future of Semicon and E-mobility in Europe

The future of semiconductors and e-mobility in Europe is set to be a dynamic and innovative ...
EE Times

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SUMMARY

New Low Cost Plasma Desmear System

Designed exclusively for low volume and startup PCB manufacturers, the MK-II ECO is an unbeatable value at just \$49,900. It features a 24" by 18" horizontal shelf for desmear and etch back.
Plasma Etch



Introducing ASE's Integrated Design Ecosystem™ (IDE)

ASE's IDE is a collaborative design toolset optimized to systematically boost advanced package architecture across its VIPack™ platform.
ASE




China makes key progress in closing mobile memory chip gap with South Korea, US as tech war rages

China is making significant strides in closing the mobile memory chip gap with South Korea and ...
South China Morning Post

SUMMARY

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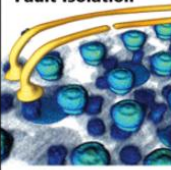
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Calendar

- [Dec 1, 2023: San Diego IMAPS & ACerS Winter Social](#)
- [Dec 7, 2023: SiC—Silicon Carbide Webinar Series](#)
- [Dec 13, 2023: SEMICON Japan 2023](#)
- [Jan 7, 2024: ISS 2024—Industry Strategy Symposium](#)

New Low Cost Plasma Desmear System

Designed exclusively for low volume and startup PCB manufacturers, the MK-II ECO is an unbeatable value at just \$49,900. It features a 24" by 18" horizontal shelf for desmear and etch back.


Plasma Etch



Introducing ASE's Integrated Design Ecosystem™ (IDE)

ASE's IDE is a collaborative design toolset optimized to systematically boost advanced package architecture across its VIPack™ platform.

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Test Your Knowledge

What is Valentina Tereshkova's claim to fame?
See answer below.

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Surfx atmospheric pressure argon plasma enables in-line particle-free cleaning of contaminants and reduction of metal oxides. Turnkey systems and integrator modules available.

Surfx Technologies



Press Releases

[Tresky unveils the photonics bonder for sub-micron use in nano- and optoelectronics](#)

The German DIE Bonder specialist Tresky GmbH is excited to introduce its latest product, the highly precise photonics bonder. The recently developed bonder is based ...

Tresky GmbH

[EV Group Expands Production Capacity at Corporate Headquarters](#)

EV Group (EVG) announced that it has completed construction work for the next expansion phase of its corporate headquarters. The new "Manufacturing V" facility, ...

EV Group

Battery Management System (BMS) for EV: who will take the lead?

Globally, the growth of vehicle electrification is accelerating across major markets. By 2028, the global light vehicle market is projected to reach 93 million units, with ...

YOLE Group

STMicroelectronics reveals precision digital power monitor with MIPI I3C support

STMicroelectronics has introduced the TSC1641 precision digital current, voltage, and power monitor with high-precision input channels and support for the MIPI I3C[1]

STMicroelectronics

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AI Technology, Inc.

Quote of the Day

"The secret of success is sincerity. Once you can fake that you've got it made."

Jean Giraudoux

IR Laser Cleave Technology for 3D Packaging and Scaling

Ultra-thin layer transfer from silicon carriers with nanometer precision using an IR laser and inorganic release layers revolutionizes 3D packaging & logic scaling.



EV Group

Permanent Bonding Material

In this paper, a novel negative-tone, photosensitive, polymeric bonding material is proposed that can be used as a dielectric enabling polymer/metal hybrid bonding.



Brewer Science

The day was Nov 30. What year was it?

Folies Bergere Stage First Revue

Once a hall for operettas, pantomime, and vaudeville, the Folies Bergère in Paris introduces an elaborate revue featuring women in sensational costumes.



See the answer below.

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Royce Instruments

Cartoon of the Day



"If you are not completely satisfied with your purchase, eat a big turkey sandwich. I always feel satisfied after a big turkey sandwich."

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Nordson Electronics Solutions

Test Your Knowledge Answer

What is Valentina Tereshkova's claim to fame?

Answer: She was the first woman in space on June 6, 1963.

What Year Was It Answer

Folies Bergere Stage First Revue

Answer: November 30, 1886

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